



Material Content Data Sheet



Sales Product Name				IPD096N08N3 G		Issued		19. January 2018	
MA#				MA001216300					
Package				PG-TO252-3-313		Weight*		318.58 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	2.461	0.77	0.77	7725	7725	
leadframe	inorganic material	phosphorus	7723-14-0	0.044	0.01		139		
	non noble metal	iron	7439-89-6	0.147	0.05		462		
	non noble metal	copper	7440-50-8	147.096	46.18	46.24	461733	462334	
	non noble metal	aluminium	7429-90-5	4.195	1.32	1.32	13168	13168	
wire	non noble metal	aluminium	7429-90-5	4.195	1.32	1.32	13168	13168	
encapsulation	organic material	carbon black	1333-86-4	1.380	0.43		4331		
	plastics	epoxy resin	-	24.148	7.58		75798		
	inorganic material	silicondioxide	60676-86-0	112.458	35.30	43.31	353004	433133	
leadfinish	non noble metal	tin	7440-31-5	3.740	1.17	1.17	11740	11740	
plating	inorganic material	phosphorus	7723-14-0	0.003	0.00		11		
	non noble metal	nickel	7440-02-0	1.421	0.45	0.45	4459	4470	
solder	non noble metal	tin	7440-31-5	0.046	0.01		143		
	noble metal	silver	7440-22-4	0.057	0.02		179		
	non noble metal	lead	7439-92-1	2.177	0.68	0.71	6833	7155	
heatspreader	inorganic material	phosphorus	7723-14-0	0.006	0.00		18		
	non noble metal	iron	7439-89-6	0.019	0.01		60		
	non noble metal	copper	7440-50-8	19.177	6.02	6.03	60197	60275	
*deviation	< 10%		Sum in total:			100.00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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